

WHAT IS CLAIMED IS:

1. A method of manufacturing an electronic part  
in which that side of an insulating member sandwiched  
between conductor film and a lower conductor layer  
5 which is adjacent to said conductor film, a conductor  
portion connected from said lower conductor layer is  
exposed, comprising

forming an opening portion having said lower  
conductor layer as a bottom in the formed area of  
10 said conductor portion from said conductor film side,  
growing metal plating layer from the bottom of  
said opening portion with said lower conductor layer  
as an electrode,

growing metal plating layer on the upper  
15 surfaces of said conductor film and said conductor  
portion with said conductor film and said conductor  
portion as electrodes after said metal plating layer  
has reached said conductor film to thereby form said  
conductor portion in said opening portion, and  
20 forming a thickness enough to form an upper conductor  
layer.

2. A method of manufacturing an electronic part  
in which on the upper surface of an insulating member  
25 covering a lower conductor layer, a conductor portion  
connected from said lower conductor layer is exposed,  
comprising

forming conductor film on the upper surface of  
said insulating member and protective film formed on  
a part of said insulating member in a thickness  
direction, and thereafter forming an opening portion  
5 having said lower conductor layer as a bottom in said  
protective film and said conductor film in the formed  
area of said conductor portion,

growing metal plating layer from the bottom of  
said opening portion with said lower conductor layer  
10 as an electrode, and

growing metal plating layer on the upper  
surfaces of said conductor film and said conductor  
portion with said exposed conductor film and said  
conductor portion on which protective film is not  
15 formed as electrodes, to thereby form a thickness  
enough to form an upper conductor layer after said  
metal plating layer has reached said conductor film  
to thereby form said conductor portion in said  
opening portion.

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3. A method according to Claim 1 or 2, wherein  
said exposed conductor film providing said electrode  
is set outside a product area.

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4. A method according to Claim 1 or 2, wherein  
said insulating member and said conductor film are  
made integral with each other in advance.

5. An electronic part having structure in which  
an upper conductor layer is formed on the upper  
surface of an insulating member covering a lower  
5 conductor layer, and

said lower conductor layer and said upper  
conductor layer are connected together by a conductor  
portion extending through said insulating member,  
wherein said conductor portion forming the connection  
10 between said lower conductor layer and said upper  
conductor layer, and an upper predetermined thickness  
in said upper conductor layer are formed by only the  
precipitation of a metal by electroplating.